262,144-word × 16-bit Dynamic Random Access Memory

HITACHI

ADE-203-292B (Z) Rev. 2.0 Jul. 18, 1996

Description

The Hitachi HM51W4260C is CMOS dynamic RAM organized as 262,144-word \times 16-bit. HM51W4260C has realized higher density, higher performance and various functions by employing $0.8~\mu m$ CMOS process technology and some new CMOS circuit design technologies. The HM51W4260C offers Fast Page Mode as a high speed access mode. Multiplexed address input permits the HM51W4260C to be packaged in standard 400-mil 44-pin plastic TSOPII. Internal refresh timer enables self refresh operation.

Features

- Single 3.3 V (±0.15 V) (HM51W4260C-6R) (±0.3 V) (HM51W4260C-7/8)
- High speed
 - Access time: 60 ns/70 ns/80 ns (max)
- Low power dissipation
 - Active mode: 468 mW/396 mW/342 mW (max)
 - Standby mode: 6.9 mW (max) (HM51W4260C-6R)

7.2 mW (max) (HM51W4260C-7/8)

0.35 mW (max) (L-version) (HM51W4260CL-6R)

0.36 mW (max) (L-version) (HM51W4260CL-7/8)

- Fast page mode capability
- 512 refresh cycles: 8 ms

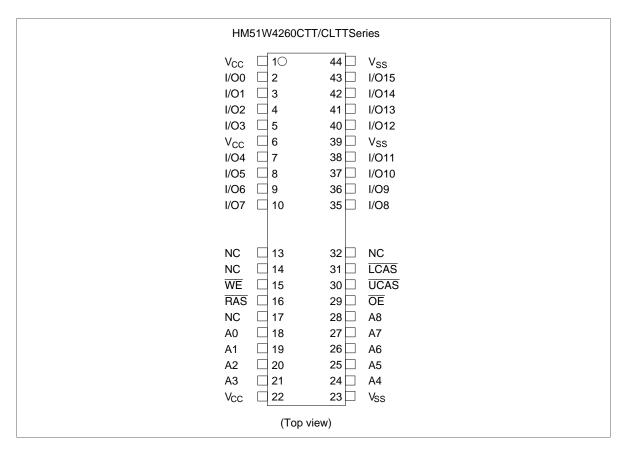
128 ms (L-version)

- 2 CAS-byte control
- 3 variations of refresh
 - RAS-only refresh
 - CAS-before-RAS refresh
 - Self refresh
- Battery back up operation (L-version)

Ordering Information

Type No.	Access time	Package
HM51W4260CTT-6R HM51W4260CTT-7	60 ns 70 ns	400-mill 44-pin plastic TSOP II (TTP-44/40DB)
HM51W4260CTT-8 HM51W4260CLTT-6R	80 ns 60 ns	
HM51W4260CLTT-7 HM51W4260CLTT-8	70 ns 80 ns	

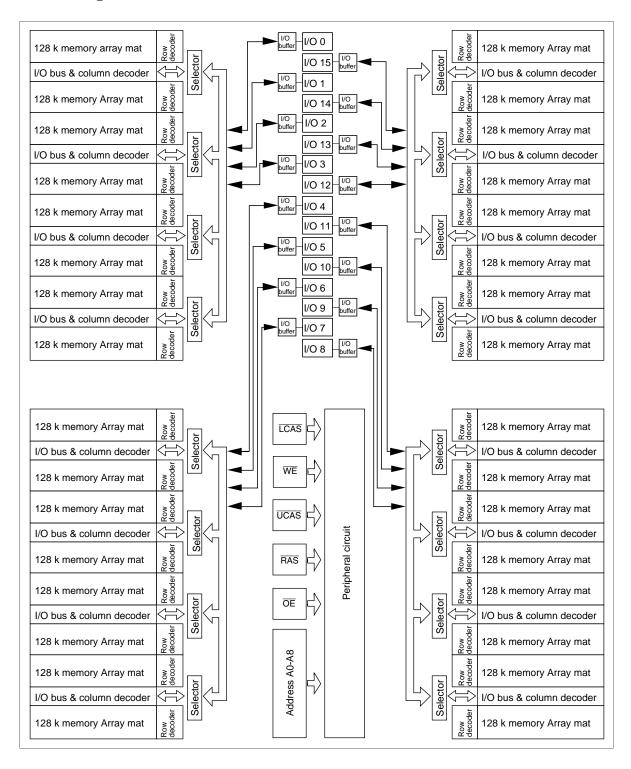
Pin Arrangement



Pin Description

Pin name	Function	
A0 to A8	Address input Row address Column address Refresh address	A0 to A8 A0 to A8 A0 to A8
I/O0 to I/O15	Data-in/data-out	
RAS	Row address strobe	
UCAS, LCAS	Column address strok	ре
WE	Read/write enable	
ŌĒ	Output enable	
V _{cc}	Power supply	
V _{ss}	Ground	
NC	No connection	

Block Diagram



Operation Mode

The HM51W4260C series has the following 11 operation modes.

- 1. Read cycle
- 2. Early write cycle
- 3. Delayed write cycle
- 4. Read-modify-write cycle
- 5. \overline{RAS} -only refresh cycle
- 6. \overline{CAS} -before- \overline{RAS} refresh cycle
- 7. Self refresh cycle
- 8. Fast page mode read cycle
- 9. Fast page mode early write cycle
- 10. Fast page mode delayed write cycle
- 11. Fast page mode read-modify-write cycle

Inputs						
RAS	LCAS	UCAS	WE	ŌĒ	Output	Operation
Н	Н	Н	D	D	Open	Standby
Н	L	L	Н	L	Valid	Standby
L	L	L	Н	L	Valid	Read cycle
L	L	L	L*2	D	Open	Early write cycle
L	L	L	L*2	Н	Undefined	Delayed write cycle
L	L	L	H to L	L to H	Valid	Read-modify-write cycle
L	Н	Н	D	D	Open	RAS-only refresh cycle
H to L	Н	L	D	D	Open	CAS-before-RAS refresh cycle
	L	Н				Self refresh cycle
	L	L				
L	H to L	H to L	Н	L	Valid	Fast page mode read cycle
L	H to L	H to L	L*2	D	Open	Fast page mode early write cycle
L	H to L	H to L	L*2	Н	Undefined	Fast page mode delayed write cycle
L	H to L	H to L	H to L	L to H	Valid	Fast page mode read-modify-write cycle
L	L	L	Н	Н	Open	Read cycle (Output disabled)

Notes: 1. H: High(inactive) L: Low(active) D: H or L

- $2. \ t_{\text{\tiny WCS}} \geq 0 \ \text{ns} \qquad \text{Early write cycle}$
 - t_{wcs} < 0 ns Delayed write cycle
- Mode is determined by the OR function of the UCAS and LCAS. (Mode is set by the earliest of UCAS and LCAS active edge and reset by the latest of UCAS and LCAS inactive edge.)
 However write OPERATION and output HIZ control are done independently by each UCAS, LCAS.
 - ex. if $\overline{RAS} = H$ to L, $\overline{LCAS} = L$, $\overline{UCAS} = H$, then \overline{CAS} -before- \overline{RAS} refresh cycle is selected.

Absolute Maximum Ratings

Parameter	Symbol	Value	Unit	
Voltage on any pin relative to V _{ss}	V _T	-0.5 to +4.6	V	
Supply voltage relative to V _{ss}	V _{cc}	-0.5 to +4.6	V	
Short circuit output current	lout	50	mA	
Power dissipation	P _T	1.0	W	
Operating temperature	Topr	0 to +70	°C	
Storage temperature	Tstg	-55 to +125	°C	

Recommended DC Operating Conditions (Ta = $0 \text{ to } +70^{\circ}\text{C}$)

Parameter	Symbol	Min	Тур	Max	Unit	Notes
Supply voltage	V_{SS}	0	0	0	V	2
	V _{cc} (HM51W4260C-6R)	3.15	3.3	3.45	V	1, 2
	V _{cc} (HM51W4260C-7/8)	3.0	3.3	3.6	V	1, 2
Input high voltage	V _{IH}	2.0		V _{cc} + 0.3	V	1
Input low voltage	V _{IL}	-0.3		0.8	V	1

Notes: 1. All voltage referred to V_{SS}

^{2.} The supply voltage with all $V_{\rm CC}$ pins must be on the same level. The supply voltage with all $V_{\rm SS}$ pins must be on the same level.

DC Characteristics

(Ta = 0 to 70°C, V_{CC} = 3.3 V ± 0.15 V, V_{SS} = 0 V) (HM51W4260C-6R)*⁵ (Ta = 0 to 70°C, V_{CC} = 3.3 V ± 0.3 V, V_{SS} = 0 V) (HM51W4260C-7/8) *⁵

		НМ5	1W42	60C					
		-6R		-7		-8			
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Unit	Test conditions
Operating current*1, *2	I _{CC1}	_	130	_	110	_	95	mΑ	$\overline{\text{RAS}}$, $\overline{\text{UCAS}}$ or $\overline{\text{LCAS}}$ cycling $t_{\text{RC}} = \min$
Standby current	I _{CC2}	_	2	_	2	_	2	mA	TTL interface RAS, UCAS, LCAS = V _{IH} Dout = High-Z
		_	1		1		1	mA	CMOS interface RAS, UCAS, LCAS, WE, $\overline{OE} \ge V_{CC} - 0.2 \text{ V}$ Dout = High-Z
Standby current (L-version)		_	100		100		100	μА	CMOS interface RAS, UCAS, LCAS, OE, WE ≥ V _{cc} – 0.2 V Dout = High-Z
RAS-only refresh current*2	I _{CC3}	_	125	_	105	_	92	mΑ	$t_{RC} = min$
Standby current*1	I _{CC5}	_	5	_	5	_	5	mA	$\overline{RAS} = V_{IH}$, \overline{UCAS} or $\overline{LCAS} = V_{IL}$ Dout = enable
CAS-before-RAS refresh current*2	I _{CC6}	_	125	_	105	_	92	mA	t _{RC} = min
Fast page mode current*1, *3	I _{CC7}	_	115	_	95	_	80	mA	$t_{PC} = min$
Battery back up current*4 (Standby with CBR refresh) (L-version)	I _{CC10}	_	100	_	100	_	100	μΑ	Standby: CMOS interface Dout = High-Z CBR refresh: t_{RC} = 250 μ s $t_{RAS} \le 1 \mu$ s, \overline{UCAS} , \overline{LCAS} = V_{IL} \overline{WE} , \overline{OE} = V_{IH}
Self-refresh mode current (HM51W4260C)	I _{CC11}	_	1	_	1	_	1	mA	CMOS interface RAS, UCAS, LCAS ≤ 0.2 V, Dout = High-Z
Self-refresh mode current (HM51W4260CL)		_	100	_	100	_	100	μА	CMOS interface RAS, UCAS, LCAS ≤ 0.2 V, Dout = High-Z
Input leakage current	I _{LI}	-10	10	-10	10	-10	10	μΑ	0 V ≤ Vin ≤ 4.6 V
Output leakage current	I _{LO}	-10	10	-10	10	-10	10	μΑ	0 V ≤ Vout ≤ 4.6 V, Dout = disable
Output high voltage	V _{OH}	2.4	V_{cc}	2.4	V_{cc}	2.4	V_{cc}	V	High lout = -2 mA
Output low voltage	V _{OL}	0	0.4	0	0.4	0	0.4	V	Low lout = 2 mA

Notes: 1. I_{cc} depends on output load condition when the device is selected. I_{cc} max is specified at the output open condition.

- 2. Address can be changed once or less while $\overline{RAS} = V_{IL}$.
- 3. Address can be changed once or less while \overline{UCAS} and $\overline{LCAS} = V_{IH}$.
- 4. $V_{IH} \ge V_{CC} 0.2 \text{ V}, \ 0 \le V_{IL} \le 0.2 \text{ V}, \ Address can be changed once or less while } \overline{RAS} = V_{IL}$
- 5. All the $V_{\rm CC}$ pins shall be supplied with the same voltage. And all the $V_{\rm SS}$ pins shall be supplied with the same voltage.

Capacitance (Ta = +25°C,
$$V_{CC}$$
 = 3.3 V ± 0.15 V) (HM51W4260C-6R) (Ta = +25°C, V_{CC} = 3.3 V ± 0.3 V) (HM51W4260C-7/8)

Parameter	Symbol	Тур	Max	Unit	Notes
Input capacitance (Address)	C ₁₁	_	5	pF	1
Input capacitance (Clocks)	C ₁₂	_	7	pF	1
Output capacitance (Data-in, Data-out)	C _{I/O}	_	10	pF	1, 2

Notes: 1. Capacitance measured with Boonton Meter or effective capacitance measuring method.

2. \overline{UCAS} and $\overline{LCAS} = V_{IH}$ to disable Dout

$$\begin{array}{l} \textbf{AC Characteristics} & (Ta=0 \text{ to } 70^{\circ}\text{C}, \, V_{\text{CC}}=3.3 \text{ V} \pm 0.15 \text{ V}, \, V_{\text{SS}}=0 \text{ V}) \\ & (HM51W4260\text{C-6R})^{*1, \, *14, \, *15, \, *17, \, *18} \\ & (Ta=0 \text{ to } 70^{\circ}\text{C}, \, V_{\text{CC}}=3.3 \text{ V} \pm 0.3 \text{ V}, \, V_{\text{SS}}=0 \text{ V}) \\ & (HM51W4260\text{C-7/8})^{*1, \, *14, \, *15, \, *17, \, *18} \\ \end{array}$$

Test Conditions

• Input rise and fall time: 5 ns

• Input timing reference levels: 0.8 V, 2.0 V

• Input levels: 0 V, 3 V

• Output load: 1 TTL gate + C_L (50 pF) (HM51W4260C-6R) (Including scope and jig)

1 TTL gate + C_L (100 pF) (HM51W4260-7/8) (Including scope and jig)

Read, Write, Read-Modify-Write and Refresh Cycles (Common Parameters)

		НМ5	1W42600		1				
		-6R		-7		-8			
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Unit	Notes
Random read or write cycle time	t _{RC}	110	_	130	_	150	_	ns	
RAS precharge time	t _{RP}	40	_	50	_	60		ns	
RAS pulse width	t _{RAS}	60	10000	70	10000	80	10000	ns	
CAS pulse width	t _{CAS}	15	10000	20	10000	20	10000	ns	23
Row address setup time	t _{ASR}	0	_	0	_	0	_	ns	
Row address hold time	t _{RAH}	10	_	10	_	10	_	ns	
Column address setup time	t _{ASC}	0	_	0	_	0	_	ns	19
Column address hold time	t _{CAH}	15	_	15	_	15	_	ns	19
RAS to CAS delay time	t _{RCD}	20	45	20	50	20	60	ns	8
RAS to column address delay time	t _{RAD}	15	30	15	35	15	40	ns	9
RAS hold time	t _{RSH}	15	_	20	_	20	_	ns	
CAS hold time	t _{CSH}	60	_	70	_	80	_	ns	
CAS to RAS precharge time	t _{CRP}	10	_	10	_	10	_	ns	20
OE to Din delay time	t _{odd}	15	_	20	_	20	_	ns	
OE delay time from Din	t _{DZO}	0	_	0	_	0	_	ns	
CAS setup time from Din	t _{DZC}	0	_	0	_	0	_	ns	
Transition time (rise and fall)	t _T	3	50	3	50	3	50	ns	7
Refresh period	t _{REF}	_	8	_	8	_	8	ms	
Refresh period (L-version)	t _{REF}	_	128	_	128	_	128	ms	

Read Cycle

		НМ5	1W4260	С				Ī	
		-6R		-7		-8			
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Unit	Notes
Access time from RAS	t _{RAC}	_	60		70	_	80	ns	2, 3
Access time from CAS	t _{CAC}	_	15	_	20	_	20	ns	3, 4, 13
Access time from address	t _{AA}	_	30	_	35	_	40	ns	3, 5, 13
Access time from OE	t _{OAC}	_	15	_	20	_	20	ns	3, 23
Read command setup time	t _{RCS}	0	_	0	_	0		ns	19
Read command hold time to CAS	t _{RCH}	0	_	0	_	0	_	ns	16, 20
Read command hold time to RAS	t _{RRH}	0	_	0	_	0	_	ns	16
Column address to RAS lead time	t _{RAL}	30	_	35	_	40	_	ns	
Output buffer turn-off time	t _{OFF1}	0	15	0	15	0	15	ns	6
Output buffer turn-off to OE	t _{OFF2}	0	15	0	15	0	15	ns	6
CAS to Din delay time	t _{CDD}	15	_	15	_	15	_	ns	

Write Cycle

		HM51W4260C							
		-6R		-7		-8			
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Unit	Notes
Write command setup time	t _{wcs}	0	_	0	_	0	_	ns	10, 19
Write command hold time	t _{wch}	15	_	15	_	15	_	ns	19
Write command pulse width	t _{wP}	10	_	10	_	10	_	ns	
Write command to RAS lead time	t _{RWL}	15	_	20	_	20	_	ns	
Write command to CAS lead time	t _{CWL}	15	_	20	_	20	_	ns	21
Data-in setup time	t _{DS}	0	_	0	_	0	_	ns	11
Data-in hold time	t _{DH}	15	-	15	_	15	_	ns	11
CAS to OE delay time	t _{COD}	_	0	_	0	_	0	ns	23

Read-Modify-Write Cycle

		Ī							
		-6R		-7		-8			
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Unit	Notes
Read-modify-write cycle time	t _{RWC}	150	_	180	_	200	_	ns	
RAS to WE delay time	t _{RWD}	80	_	95	_	105	_	ns	10
CAS to WE delay time	t _{CWD}	35	_	45	_	45	_	ns	10
Column address to WE delay time	t _{AWD}	50	_	60	_	65	_	ns	10
OE hold time from WE	t _{OEH}	15	_	20	_	20	_	ns	

Refresh Cycle

		HM51W4260C							
		-6R		-7		-8			
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Unit	Note
CAS setup time (CBR refresh cycle)	t _{CSR}	10	_	10	_	10	_	ns	19
CAS hold time (CBR refresh cycle)	t _{CHR}	10	_	10	_	10	_	ns	20
RAS precharge to CAS hold time	t _{RPC}	10	_	10	_	10		ns	19
CAS precharge time in normal mode	t _{CPN}	10	_	10	_	10	_	ns	22

Fast Page Mode Cycle

		HM51W4260C							
		-6R		-7		-8			
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Unit	Notes
Fast page mode cycle time	t _{PC}	40	_	45	_	50	_	ns	
Fast page mode CAS precharge time	t _{CP}	10	_	10	_	10	_	ns	22
Fast page mode RAS pulse width	t _{RASC}	_	100000	_	100000	_	100000	ns	12
Access time from CAS precharge	t _{ACP}	_	35	_	40	_	45	ns	3, 13, 20
RAS hold time from CAS precharge	t _{RHCP}	35	_	40	_	45	_	ns	

Fast Page Mode Read-Modify-Write Cycle

		HM51W4260C							
		-6R		-7		-8			
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Unit	Notes
Fast page mode read-modify-write cycle CAS precharge to WE delay time	t _{CPW}	55	_	65	_	70	_	ns	
Fast page mode read-modify-write cycle time	t _{PCM}	80	_	95	_	100	_	ns	

Self Refresh Mode

HM51W4260C

		-6R		-7		-8			
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Unit	Notes
RAS pulse width (self-refresh)	t _{RASS}	100	_	100	_	100	_	μs	24, 25, 26, 27
RAS precharge time (self-refresh)	t _{RPS}	110	_	130	_	150	_	ns	
CAS hold time (self-refresh)	t _{CHS}	-50	_	-50	_	-50	_	ns	21

Notes: 1. AC measurements assume $t_T = 5$ ns.

- 2. Assumes that $t_{RCD} \le t_{RCD}$ (max) and $t_{RAD} \le t_{RAD}$ (max). If t_{RCD} or t_{RAD} is greater than the maximum recommended value shown in this table, t_{RAC} exceeds the value shown.
- 3. Measured with a load circuit equivalent to 1 TTL load and 50 pF (HM51W4260C-6R), 1 TTL load and 100 pF (HM51W4260C-7/8) (V_{OH} = 2.0 V, V_{OL} = 0.8 V).
- 4. Assumes that $t_{RCD} \ge t_{RCD}$ (max) and $t_{RAD} \le t_{RAD}$ (max).
- 5. Assumes that $t_{RCD} \le t_{RCD}$ (max) and $t_{RAD} \ge t_{RAD}$ (max).
- t_{OFF} (max) defines the time at which the output achieves the open circuit condition and is not referred to output voltage levels.
- 7. V_{IH} (min) and V_{IL} (max) are reference levels for measuring timing of input signals. Also, transition times are measured between V_{IH} and V_{IL} .
- Operation with the t_{RCD} (max) limit insures that t_{RAC} (max) can be met, t_{RCD} (max) is specified as a reference point only, if t_{RCD} is greater than the specified t_{RCD} (max) limit, then access time is controlled exclusively by t_{CAC}.
- 9. Operation with the t_{RAD} (max) limit insures that t_{RAC} (max) can be met, t_{RAD} (max) is specified as a reference point only, if t_{RAD} is greater than the specified t_{RAD} (max) limit, then access time is controlled exclusively by t_{AA} .
- 10. t_{WCS} , t_{RWD} , t_{CWD} and t_{AWD} are not restrictive operating parameters. They are included in the data sheet as electrical characteristics only: if $t_{WCS} \ge t_{WCS}$ (min), the cycle is an early write cycle and the data out pin will remain open circuit (high impedance) throughout the entire cycle; if $t_{RWD} \ge t_{RWD}$ (min), $t_{CWD} \ge t_{CWD}$ (min), $t_{AWD} \ge t_{AWD}$ (min) and $t_{CPW} \ge t_{CPW}$ (min), the cycle is a read-modify-write and the data output will contain data read from the selected cell; if neither of the above sets of conditions is satisfied, the condition of the data out (at access time) is indeterminate.
- 11. These parameters are referred to CAS leading edge in an early write cycle and to WE leading edge in a delayed write or a read-modify-write cycle.
- 12. t_{RASC} defines \overline{RAS} pulse width in fast page mode cycles.
- 13. Access time is determined by the longest among $\,t_{\text{AA}},\,t_{\text{CAC}}$ and $t_{\text{ACP}}.$

- 14. An initial pause of 100 μs is required after power up followed by a minimum of eight initialization cycles (RAS-only refresh cycle or CAS-before-RAS refresh cycle). If the internal refresh counter is used, a minimum of eight CAS-before-RAS refresh cycles is required.
- 15. In delayed write or read-modify-write cycles, $\overline{\mathsf{OE}}$ must disable output buffer prior to applying data to the device.
- 16. Either t_{RCH} or t_{RRH} must be satisfied for a read cycle.
- 17. When both UCAS and LCAS go low at the same time, all 16-bit data are written into the device.

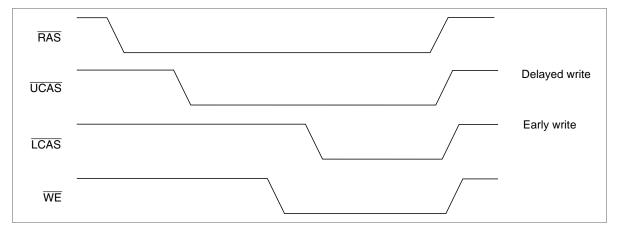
 UCAS and LCAS cannot be staggered within the same write/read cycles.
- 18. All the V_{cc} and V_{ss} pins shall be supplied with the same voltages.
- 19. t_{ASC} , t_{CAH} , t_{RCS} , t_{WCS} , t_{WCH} , t_{CSR} , t_{RPC} and t_{COD} are determined by the earlier falling edge of \overline{UCAS} or \overline{LCAS} .
- 20. t_{CRP} , t_{CHR} , t_{ACP} , t_{RCH} and t_{CPW} are determined by the later rising edge of \overline{UCAS} or \overline{LCAS} .
- 21. t_{CWL} , t_{DH} , t_{DS} and t_{CHS} should be satisfied by both $\overline{\text{UCAS}}$ and $\overline{\text{LCAS}}$.
- 22. t_{CPN} and t_{CP} are determined by the time that both \overline{UCAS} and \overline{LCAS} are high.
- 23. When output buffers are enabled once, sustain the low impedance state until valid data is obtained. When output buffer is turned on and off within a very short time, generally it causes large $V_{\rm CC}/V_{\rm SS}$ line noise, which causes to degrade $V_{\rm IH}$ min/ $V_{\rm IL}$ max level.
- 24. Please do not use t_{RASS} timing, 10 $\mu s \leq t_{\text{RASS}} \leq$ 100 μs . During this period, the device is in transition state from normal operation mode to self refresh mode. If $t_{\text{RASS}} \geq$ 100 μs , then $\overline{\text{RAS}}$ precharge time should use t_{RPS} instead of t_{RP} .
- 25. If you use distributed CBR refresh mode with 15.6 μ s interval in normal read/write cycle, CBR refresh should be executed within 15.6 μ s immediately after exiting from and before entering into self refresh mode.
- 26. If you use \overline{RAS} only refresh or CBR burst refresh mode in normal read/write cycle, 512 cycles of distributed CBR refresh with 15.6 μs interval should be executed within 8 ms immediately after exiting from and before entering into the self refresh mode.
- 27. Repetitive self refresh mode without refreshing all memory is not allowed. Once you exit from self refresh mode, all memory cells need to be refreshed before re-entering the self refresh mode again.
- 28. XXX: H or L (H: V_{IH} (min) $\leq V_{IN} \leq V_{IH}$ (max), L: V_{IL} (min) $\leq V_{IN} \leq V_{IL}$ (max)) ///: Invalid Dout

When the address, clock and input pis are not described on timing waveforms, their pins must be applied V_{IH} or V_{II} .

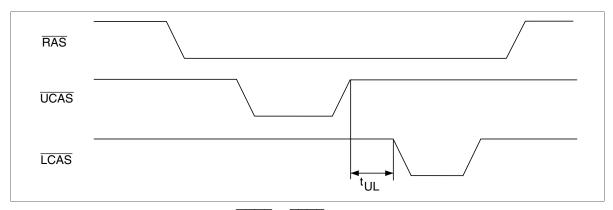
Notes concerning 2CAS control

Please do not separate the $\overline{UCAS}/\overline{LCAS}$ operation timing intentionally. However skew between $\overline{UCAS}/\overline{LCAS}$ are allowed under the following conditions.

- (1) Each of the $\overline{UCAS}/\overline{LCAS}$ should satisfy the timing specifications individually.
- (2) Different operation mode for upper/lower byte is not allowed; such as following.



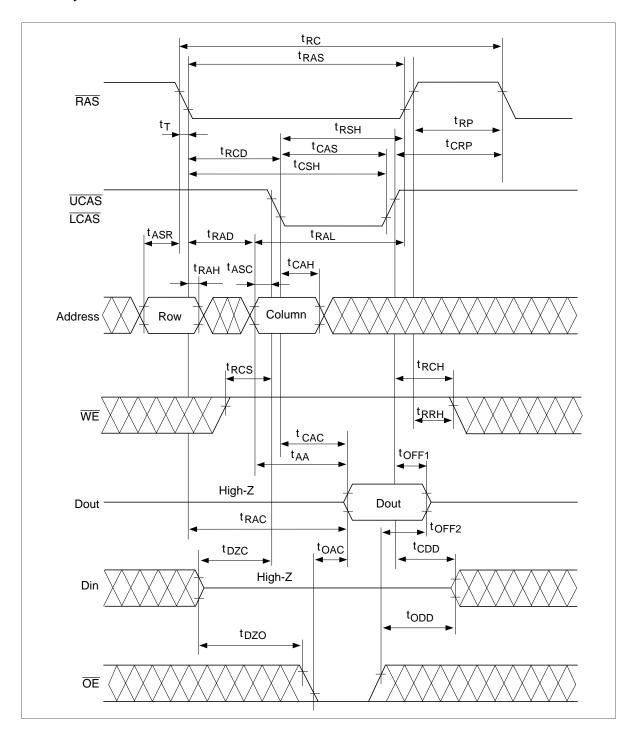
(3) Closely separated upper/lower byte control is not allowed. However when the condition $(t_{CP} \le t_{UL})$ is satisfied, fast page mode can be performed.



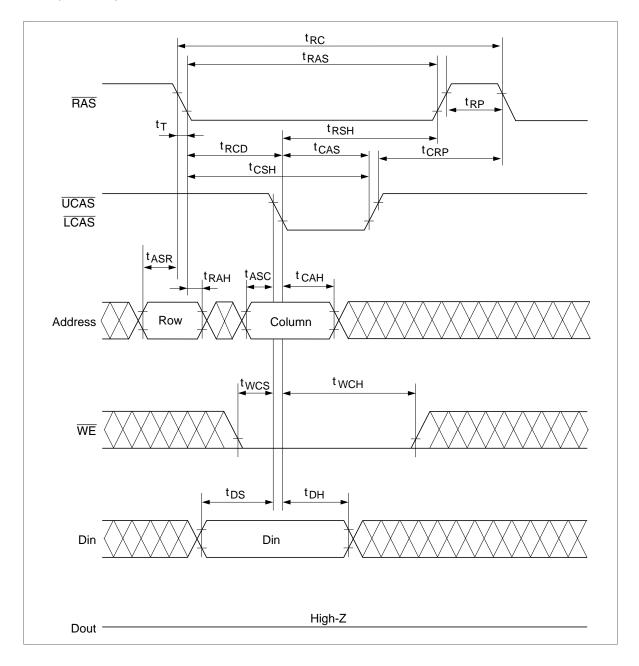
(4) Byte control operation by remaining \overline{UCAS} or \overline{LCAS} high is guaranteed.

Timing Waveforms*28

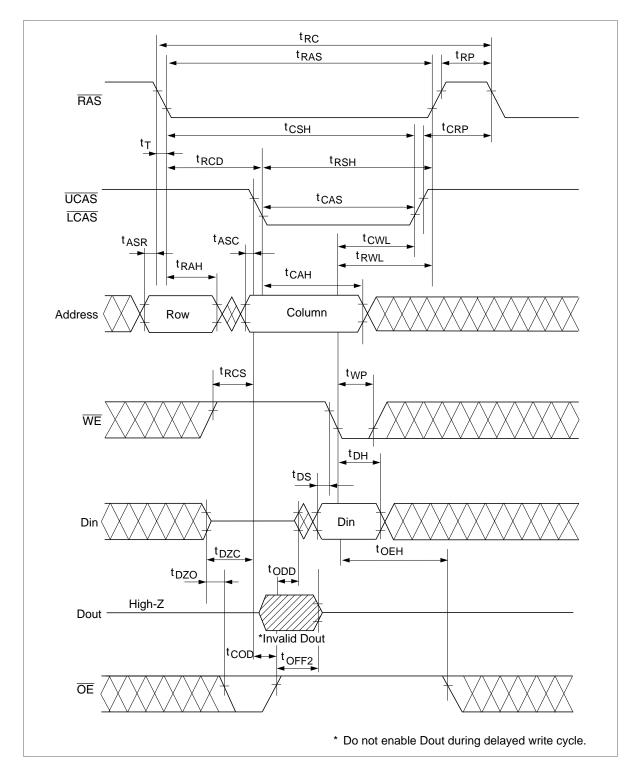
Read Cycle



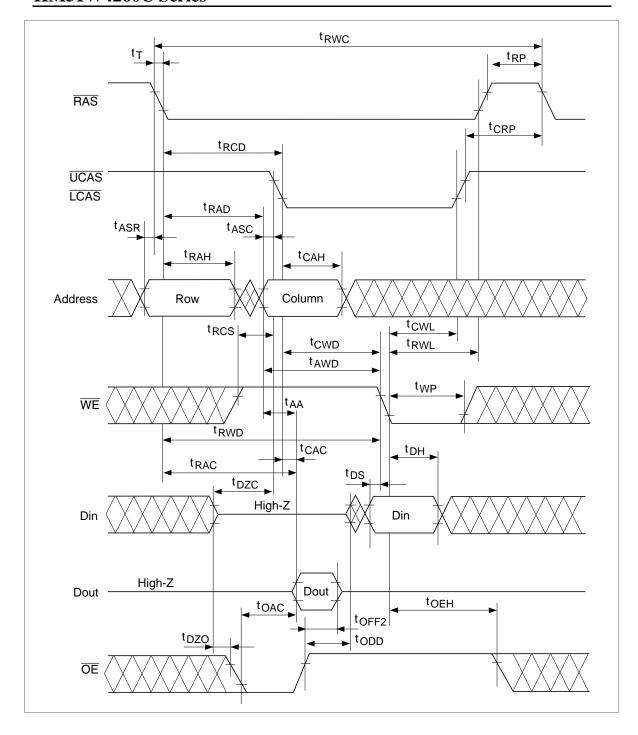
Early Write Cycle



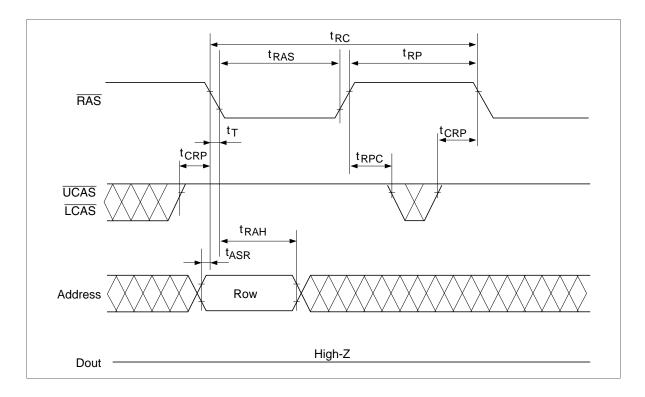
Delayed Write Cycle



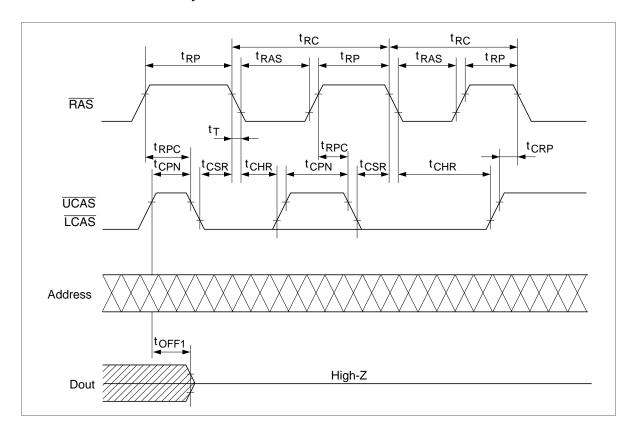
Read-Modify-Write Cycle



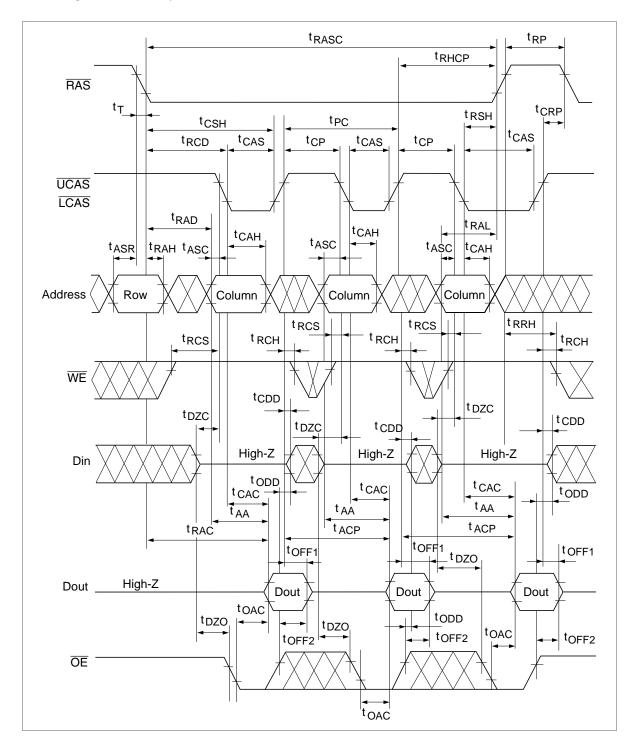
RAS-Only Refresh Cycle



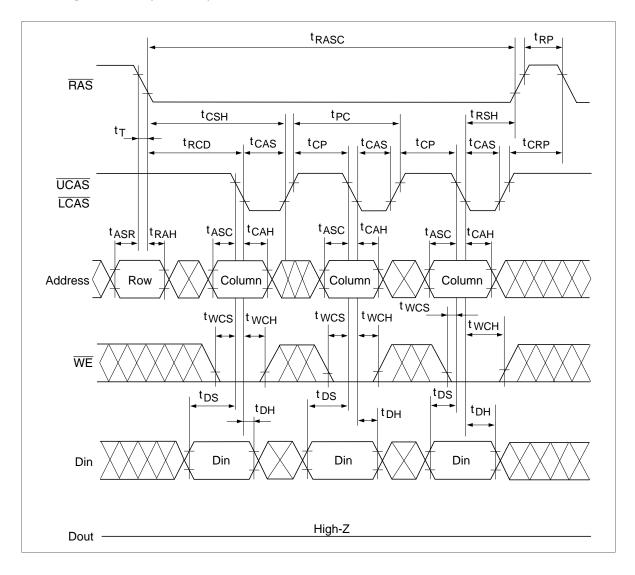
$\overline{\text{CAS}}\text{-Before-}\overline{\text{RAS}}$ Refresh Cycle



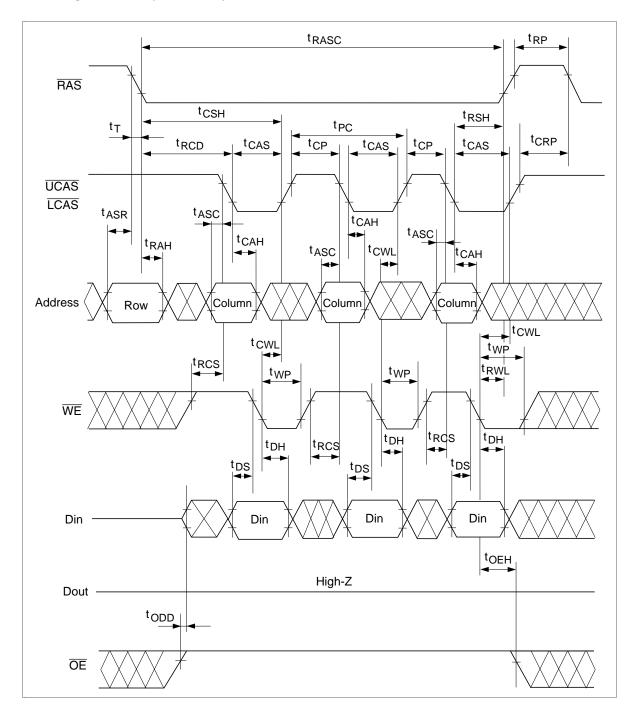
Fast Page Mode Read Cycle



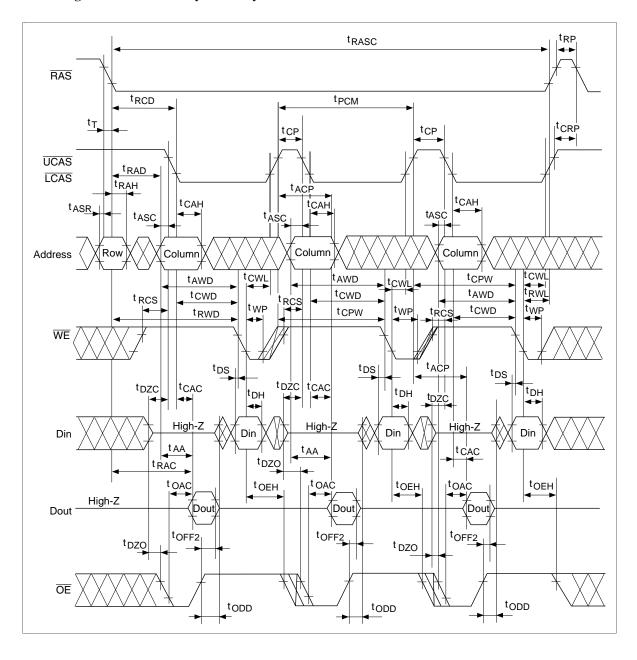
Fast Page Mode Early Write Cycle



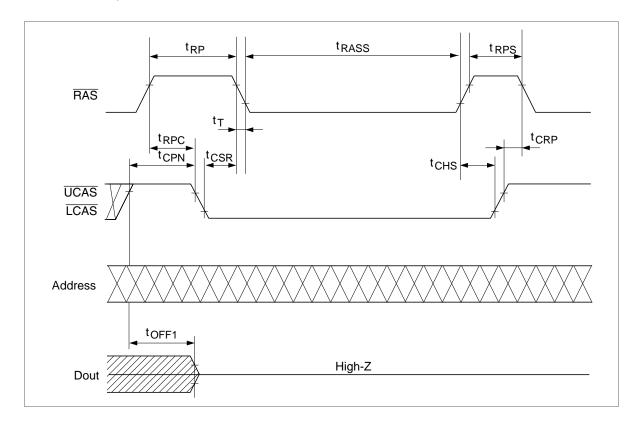
Fast Page Mode Delayed Write Cycle



Fast Page Mode Read-Modify-Write Cycle



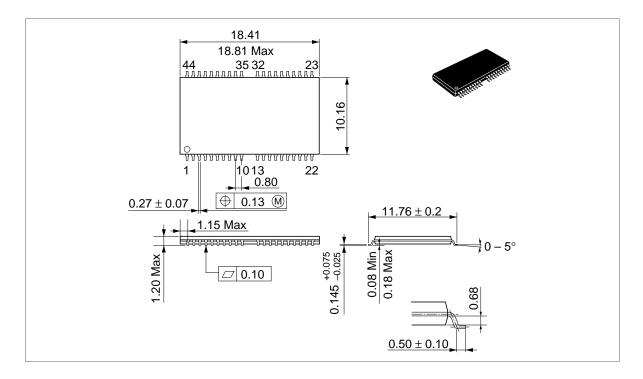
Self Refresh Cycle*24, 25, 26, 27



Package Dimensions

HM51W4260CTT/CLTT Series (TTP44/40DB)

Unit: mm



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Revision Record

Rev.	Date	Contents of Modification	Drawn by	Approved by
0.0	Sep. 7, 1994	Initial issue	S. Hatano	M. Yamamura
1.0	Feb. 2, 1995	Recommended DC Operating conditions	A. Kumata	J. Kitano
		V_{IH} min: 2.4 V to 2.0 V		
2.0	Jul. 18, 1996	Addition of HM51W4260C-6R Series		
		AC Characteristics		
		Deletion of note 27: Measured with a load circuit equivalent to 1 TTL load and 100 pF Change of note 3 Addition of note 24 Change of note 28		
		Note concerning 2CAS control		
		Addition of note 4		
		Timing waveforms		
		Deletion of notes about undefined pins Change waveforms		
		Read-modify-write cycle Fast page mode read cycle CAS-before-RAS refresh cycle Fast page mode read-modify-write cycle Self refresh cycle		